

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT7302774

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOSHIE TACHIBANA	04/01/2022
TOMOKI SASAKI	04/04/2022
NORIKAZU SAKAI	03/09/2022
YOSHIHIRO YAMAGUCHI	03/09/2022
RECEIVING PARTY DATA	
Name:	SENJU METAL INDUSTRY CO., LTD.
Street Address:	23, SENJU-HASHIDO-CHO, ADACHI-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	120-8555
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17690346
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ATTORNEY DOCKET NUMBER:	09199-2201004
NAME OF SUBMITTER:	BRYAN P. CLARK REG. NO 60,465
SIGNATURE:	/Bryan P. Clark/
DATE SIGNED:	04/26/2022
Total Attachments: 3	
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ASSIGNMENT

WHEREAS, as a below named inventor, I have invented certain new and useful improvements in

SOLDER ALLOY, SOLDER POWDER, SOLDER PASTE AND SOLDER JOINT

(Invention Title)

for which I have this day executed an application for a United States Patent (hereinafter "said application").

AND/OR

for which an application for a United States Patent was filed on 03/09/2022 (mm/dd/yyyy) and bears Application Number 17/690,346 (hereinafter "said application").

AND/OR

for which an international patent application was filed under the Patent Cooperation Treaty on _____ (mm/dd/yyyy), bearing Application No. _____ (hereinafter "said application").

AND, WHEREAS, Senju Metal Industry Co., Ltd., a corporation of Japan, having a place of business at 23, Senju-Hashido-cho, Adachi-ku, Tokyo 120-8555, Japan, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, for good and valuable consideration paid to me by said assignee, the receipt of which is hereby acknowledged, I as the inventor or as one of the inventors, hereinafter the assignor(s), do hereby assign, sell and transfer unto said assignee the full and exclusive right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries, including rights of priority under the International Convention of Paris (1883) as amended, and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, continuations-in-part, renewals and/or extensions thereof. Such assignment extends to the full ends of the terms of these applications and patents as fully and entirely as the same would have been held and enjoyed by me had this Assignment not been made.

I covenant that I am the lawful owner(s) of said application, inventions and improvements, that the same are unencumbered, that no license has been granted to make, use or vend the said inventions or improvements or any of them, and that I have the full right to make this Assignment.

And for the consideration aforesaid, I agree individually and, if applicable, jointly that I will communicate to said assignee or the representatives thereof any facts known to me respecting said inventions and improvements, and will, upon request but without expense to me, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, continuation-in-part, renewal and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts deemed necessary or expedient by said assignee or by counsel for said assignee to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This Assignment shall be binding upon my heirs, executors, administrators and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns, as the case may be, of said assignee.

1. FULL NAME OF ASSIGNOR:

Yoshie Tachibana

RESIDENCE:

Tokyo, Japan

EXECUTED this 1st day of April, 2022

Yoshie Tachibana

SIGNATURE

WITNESS:

Hiroki Tarumi

2. FULL NAME OF ASSIGNOR:

Tomoki Sasaki

RESIDENCE:

Tokyo, Japan

EXECUTED this 4th day of April, 2022

Tomoki Sasaki

SIGNATURE

WITNESS:

Hiroki Tarumi

Checked Box indicates 1 additional page for inventor signatures.

INTERNATIONAL
Application No. 17/690,346

Attorney Docket No. 09199-2201004

3. FULL NAME OF ASSIGNOR:
Norikazu Sakai

RESIDENCE:

Tokyo, Japan

EXECUTED this 9 day of March, 2022

Norikazu Sakai

SIGNATURE

WITNESS:

Kunihiro yoshihara

4. FULL NAME OF ASSIGNOR:
Yoshihiro Yamaguchi

RESIDENCE:

Tokyo, Japan

EXECUTED this 9 day of March, 2022

Yoshihiro Yamaguchi

SIGNATURE

WITNESS:

Kunihiro yoshihara